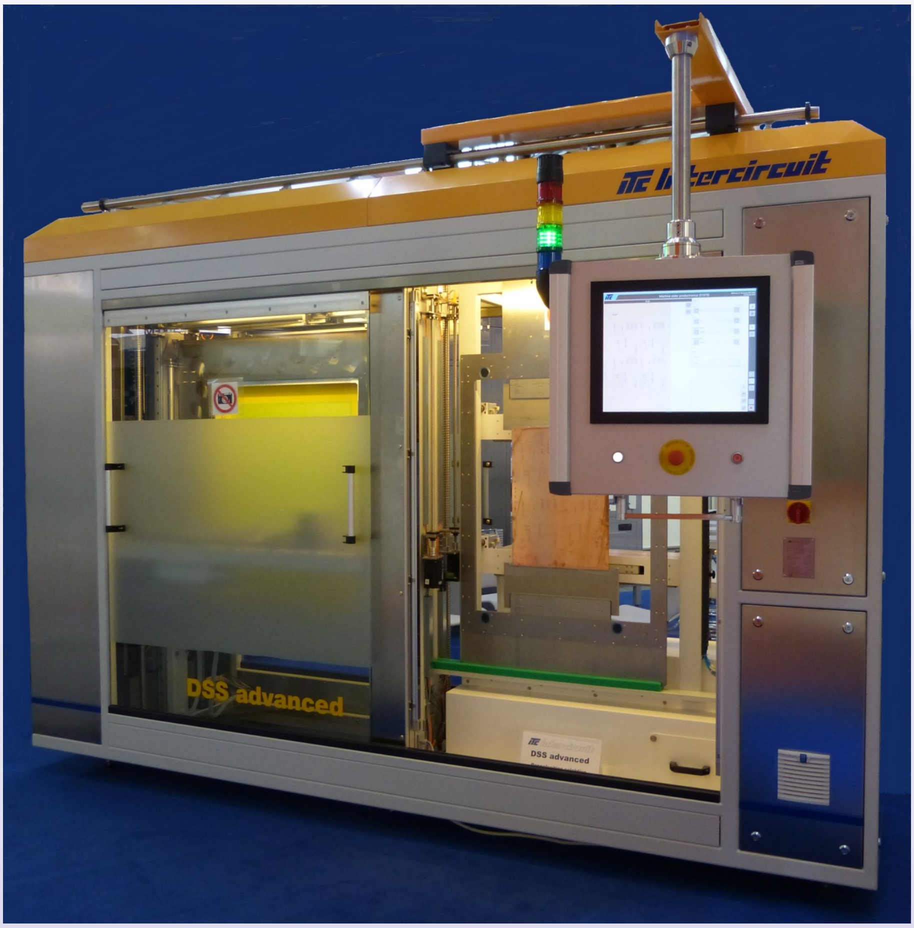
DSS advanced



Double sided selective vacuum hole filling system

The breakthrough has arrived for the

solution for true selective double sided hole filling

The system consists of the following modules

Manuel load and unload zone

Servo driven panel transport system

Double side screen holder with integrated step motor alignment

Four independently working high-resolution cameras

Patented high vacuum filling heads on both sides

The main advantages of the process and the system:

✓ Selective filling of through-holes and blind holes (double-sided) in a single process step.

✓ No masking of tooling holes or other unfilled areas.

✓ Clean and user-friendly handling of printed circuit boards after filling, paste free border areas

✓ Absolutely flat surface on the filled holes

✓ Patented high vacuum filling system

✓ Greatly reduced grinding efford

DSS advanced

Height:	**2430 mm**	**8‘**
Width:	**900 mm**	**3‘**
Length:	**3400 mm**	**11,15‘**
Connections:		
Power:	**AC 400V 3 Phasen N+G 50Hz 8KVA (AC480V G 3 Phase 60Hz 8KVA USA)**	
Compressed air:	**6 bar 90psi**	
Air exhaust:	**500m³/h**	**295 cfm**

Technical specifications

Patent pending 2019080117575900DE

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